

**MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	100	Vdc
Gate-Source Voltage	V <sub>GS</sub>	±35	Vdc
Drain Current Continuous (1)	I <sub>D</sub>	0.17	Adc
Pulsed (2)	I <sub>DM</sub>	0.68	

**THERMAL CHARACTERISTICS**

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board,* T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance Junction to Ambient	R <sub>θJA</sub>	556	°C/W
Total Device Dissipation Alumina Substrate,** T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance Junction to Ambient	R <sub>θJA</sub>	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

\*FR-5 = 1.0 x 0.75 x 0.062 in.

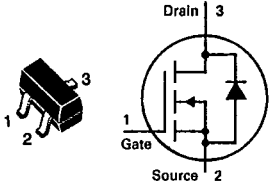
\*\*Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.

**DEVICE MARKING**

BSS123L = 5A

## BSS123L

CASE 318-03, STYLE 21  
SOT-23 (TO-236AB)



**TMOS FET  
TRANSISTOR**

**N-CHANNEL**

**ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Drain-Source Breakdown Voltage (V <sub>GS</sub> = 0, I <sub>D</sub> = 250 μA)	V(BR)DSS	100	—	—	Vdc
Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0, V <sub>DS</sub> = 100 V) T <sub>J</sub> = 25°C T <sub>J</sub> = 125°C	I <sub>DSS</sub>	—	—	15 60	μAdc
Gate-Body Leakage Current (V <sub>GS</sub> = 20 Vdc, V <sub>DS</sub> = 0)	I <sub>GSS</sub>	—	—	50	nAdc
<b>ON CHARACTERISTICS*</b>					
Gate Threshold Voltage (V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1.0 mA)	V <sub>GS(th)</sub>	0.8	—	2.8	Vdc
Static Drain-Source On-Resistance (V <sub>GS</sub> = 10 Vdc, I <sub>D</sub> = 100 mA)	r <sub>DS(on)</sub>	—	5.0	6.0	Ohms
Forward Transconductance (V <sub>DS</sub> = 25 V, I <sub>D</sub> = 100 mA)	g <sub>fs</sub>	80	—	—	mmhos
<b>DYNAMIC CHARACTERISTICS</b>					
Input Capacitance (V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0, f = 1.0 MHz)	C <sub>iss</sub>	—	20	—	pF
Output Capacitance (V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0, f = 1.0 MHz)	C <sub>oss</sub>	—	9.0	—	pF
Reverse Transfer Capacitance (V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0, f = 1.0 MHz)	C <sub>rss</sub>	—	4.0	—	pF
<b>SWITCHING CHARACTERISTICS*</b>					
Turn-On Delay Time (V <sub>CC</sub> = 30 V, I <sub>C</sub> = 0.28 A, V <sub>GS</sub> = 10 V, R <sub>GS</sub> = 50 Ω)	t <sub>d(on)</sub>	—	20	—	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	—	40	—	ns
<b>REVERSE DIODE</b>					
Diode Forward On-Voltage (I <sub>D</sub> = 0.34 A, V <sub>GS</sub> = 0 V)	V <sub>SD</sub>	—	—	1.3	V

(1) The Power Dissipation of the package may result in a lower continuous drain current.

(2) Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

\*Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.